



Material Content Data Sheet



Sales Product Name		BSC067N06LS3 G		Issued		20. July 2018		
MA#		MA001506010						
Package		PG-TDSON-8-40		Weight*		119.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.54	1.54	15395	15395
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		317	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.68	31.72	316838	317250
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	510	510
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		711	
	plastics	epoxy resin	-	6.693	5.62		56161	
	inorganic material	silicondioxide	60676-86-0	35.586	29.86	35.55	298579	355451
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12180	12180
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1389	1389
solder	noble metal	silver	7440-22-4	0.046	0.04		386	
	non noble metal	tin	7440-31-5	0.037	0.03		309	
	non noble metal	lead	7439-92-1	1.758	1.47	1.54	14747	15442
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.50	9.51	94980	95104
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		187	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.70	18.73	187036	187279
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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